Document Number: GTAH35060GX Preliminary Datasheet V1.0

# Gallium Nitride 28V 60W, RF Power Transistor

## **Description**

The GTAH35060GX is a 60W internally matched, GaN HEMT, designed for multiple applications, especially sub-6GHz MC-GSM/WCDMA/LTE/LTE-A from 700-3800MHz.

There is no guarantee of performance when this part is used in applications designed Outside of these frequencies.

# **GTAH35060GX**



### **Applications and Features**

- Suitable for wireless communication infrastructure, wideband amplifier, EMC testing, ISM etc.
- High Efficiency and Linear Gain Operations
- Thermally Enhanced Industry Standard Package
- High Reliability Metallization Process
- · Excellent thermal Stability and Excellent Ruggedness
- Compliant to Restriction of Hazardous Substances (RoHS)
  Directive 2002/95/EC

### **Important Note: Proper Biasing Sequence for GaN HEMT Transistors**

### **Turning the device ON**

- 1. Set VGS to the pinch--off (VP) voltage, typically -5 V
- 2. Turn on VDS to nominal supply voltage (28V)
- 3. Increase VGS until IDS current is attained
- 4. Apply RF input power to desired level

#### **Turning the device OFF**

- 1. Turn RF power off
- 2. Reduce VGS down to VP, typically -5 V
- 3. Reduce VDS down to 0 V
- 4. Turn off VGS

Table 1. Maximum Ratings

| Rating   | Symbol           | Value       | Unit |
|--|------------------|-------------|------|
| DrainSource Voltage  | V <sub>DSS</sub> | 150         | Vdc  |
| GateSource Voltage   | V <sub>GS</sub>  | -10,+2      | Vdc  |
| Operating Voltage  | V <sub>DD</sub>  | 40          | Vdc  |
| Maximum Forward Gate Current @ Tc = 25°C                           | Igmax            | 14          | mA   |
| Storage Temperature Range  | Tstg             | -65 to +150 | °C   |
| Case Operating Temperature   | Tc               | +150        | °C   |
| Operating Junction Temperature(See note 1)                         | T,               | +200        | °C   |
| Total Device Power Dissipation<br>(Derated above 25°C, see note 2) | Pdiss            | 70          | w    |

Note: 1. Continuous operation at maximum junction temperature will affect MTTF

2.Bias Conditions should also satisfy the following expression: Pdiss < (Tj - Tc) / RJC and Tc = Tcase

#### **Table 2. Thermal Characteristics**

| Characteristic  | Symbol | Value | Unit  |  |
|---|--------|-------|-------|--|
| Thermal Resistance, Junction to Case                          | Rejc   | 2.52  | C/W   |  |
| T <sub>C</sub> = 85°C, T <sub>J</sub> =200°C, RF CW operation | NθJC   | 2.32  | C/ VV |  |

Table 3. Electrical Characteristics (T<sub>C</sub> = 25 °C unless otherwise noted)



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#### DC Characteristics

| Characteristic                 | Conditions   | Symbol           | Min | Тур   | Max | Unit |
|--------------------------------|--|------------------|-----|-------|-----|------|
| Drain-Source Breakdown Voltage | V <sub>GS</sub> =-8V; I <sub>DS</sub> =14mA                                  | V <sub>DSS</sub> | 150 |       |     | V    |
| Gate Threshold Voltage         | Threshold Voltage $V_{DS} = 28V$ , $I_D = 14$ mA                             |                  |     | -2.7  |     | V    |
| Gate Quiescent Voltage         | V <sub>DS</sub> =28V, I <sub>DS</sub> =700mA,<br>Measured in Functional Test |                  |     | -2.27 |     | V    |

Functional Tests (In 3.4-3.6GHz Production fixture, 50 ohm system) :  $V_{DD} = 28 \text{ Vdc}$ ,  $I_{DQ} = 700 \text{ mA}$ , f = 3600 MHz, WCDMA signal,

#### Pout=12W

| Characteristic                                   | Symbol           | Min | Тур  | Max | Unit |
|--|------------------|-----|------|-----|------|
| Power Gain                                       | Gp               |     | 15   |     | dB   |
| Drain Efficiency @ P <sub>out</sub>              | Eff              |     | 34   |     | %    |
| Saturated Power by CCDF test                     | P <sub>SAT</sub> | 60  |      |     | W    |
| Input Return Loss                                | IRL              |     | -7   |     | dB   |
| Mismatch stress at all phases (Device no damage) | VSWR             |     | 10:1 |     | Ψ    |



# **Package Outline**

## Flanged ceramic package; 2 leads

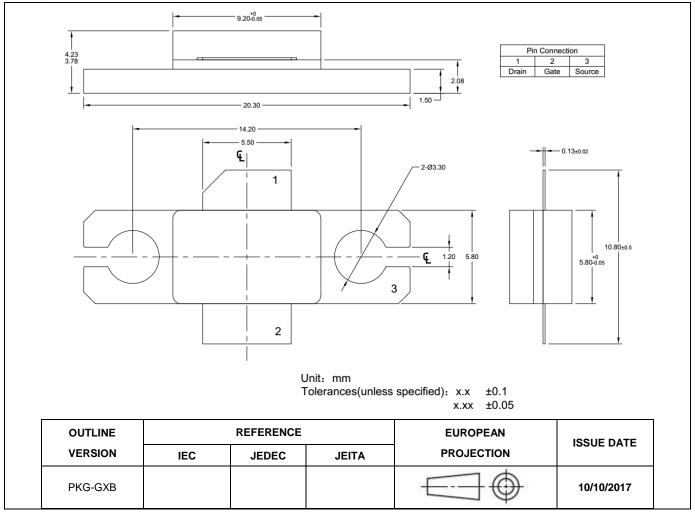


Figure 1. Package Outline PKG-G2E

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# **Revision history**

#### Table 4. Document revision history

| Date      | Revision | Datasheet Status               |
|-----------|----------|--------------------------------|
| 2017/6/26 | V1.0     | Objective Datasheet Creation   |
| 2017/7/27 | V1.0     | Preliminary Datasheet creation |

#### **Notice**

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